

Amendments to the Specification:

Please replace the paragraph beginning at page 8, line 15, with the following rewritten paragraph:

Further, (5) a solder resist film containing a photo-curing polyimide resin having a vinyleter vinylether group in a polymer side chain is known (see Patent Document 10). The solder resist film is extremely thin, and realizes high soldering resistance, chemical resistance, film formation, electric insulation property, and flexibility, but development based on alkaline aqueous solution is not realized.

Please replace the paragraph beginning at page 12, line 18, with the following rewritten paragraph:

Further, dehydration reaction occurs due to ring closure in imidizing the photosensitive polyimide precursor, so that its volume contracts. Thus, the film thickness is decreased and the size is less stabilized. Alternatively, it is necessary to remove an acetyl acryloyl group by heat depending on a kind of photosensitive polyimide, so that the film thickness may be largely decreased at this time.

Please replace the paragraph beginning at page 180, line 15, with the following rewritten paragraph:

In the example shown in Fig. 1, the comb-shaped circuit 10 includes an electrode terminal 11 and comb-shaped lines 12 and 13, and the comb-shaped circuit 20 includes an electrode terminal 21 and comb-shaped lines 22 and 23. Note that, as to the lines 12, 13, 22, and 23, for convenience in description, each of lines lines 12 and 22

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corresponding to ridges of the combs is referred to as a "trunk line", and each of the lines 13 and 23 corresponding to tooth of the combs is referred to as a "brunch line".